PRODUCT DATA SHEET

To learn more about JGSEMI, please visit our website at

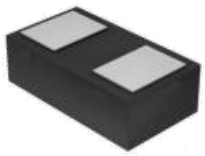
Datasheet Resources Samples

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

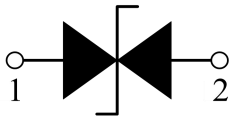
PESD5V0L1UL

Bi-directional ESD Protection Diode in DFN1006 Package

Features



- Capacitance: 15pF(typ.)
- Reverse Working Voltage: 5V
- IEC 61000-4-2 (ESD Air): ±25KV IEC 61000-4-2 (ESD Contact): ±25KV IEC 61000-4-5 (Lightning 8/20μs): 8A



Applications

- Smart Phone and Tablet PC
- TV and Set Top Box
- Wearable Devices
- PDA

Limiting Values(T_A = 25 °C, unless otherwise specified)

Symbol	Parameter	Conditions	Min	Max	Unit
V_{ESD}	Electrostatic Discharge Voltage	IEC 61000-4-2; Contact Discharge	-	±25	kV
		IEC 61000-4-2; Air Discharge	-	±25	kV
P_{PP}	Peak Pulse Power	t_P = 8/20 μs	-	80	W
I_{PPM}	Rated Peak Pulse Current	t_P = 8/20 μs	-	8	A
T_A	Ambient Temperature Range	-	-55	125	℃
T_{stg}	Storage Temperature Range	-	-55	150	℃

Electrical Characteristics(T_A = 25 °C, unless otherwise specified)

Symbol	Parameter	Conditions	Min	Typ.	Max	Unit
V_{RWM}	Reverse Working Voltage	T_A = 25 °C	-	-	5.0	V
V_{BR}	Breakdown Voltage	I_R = 1mA; T_A = 25 °C	5.6	6.5	8.4	V
I_R	Reverse Leakage Current	V_{RWM} = 5V; T_A = 25 °C	-	-	0.1	μA
V_C	Clamping Voltage	I_{PP}=8A, t_P =8/20μs	-	-	10	V
C_J	Junction Capacitance	V_R = 0V, f = 1 MHz	-	15	18	pF

Typical Characteristics

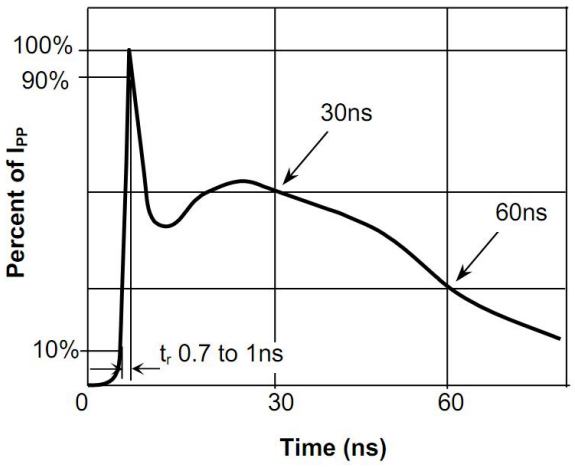


Fig.1 Pulse Waveform-ESD(IEC61000-4-2)

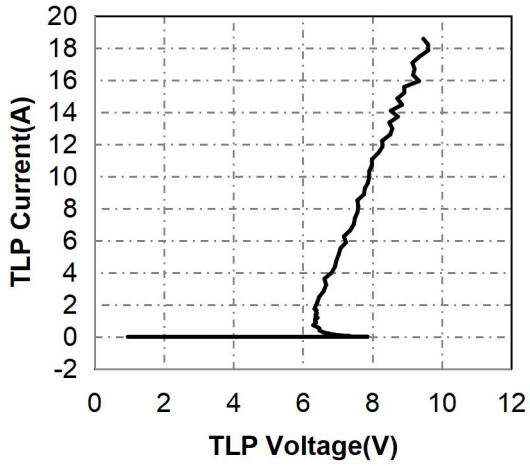


Fig.2 Transmission Line Pulse (TLP)

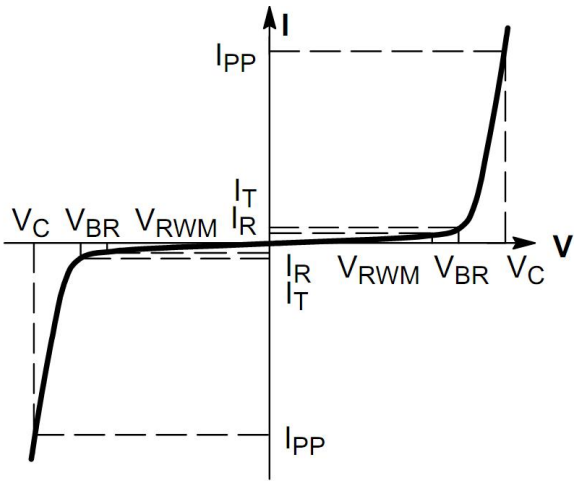


Fig.3 V-I Characteristics for Bidirectional Diode

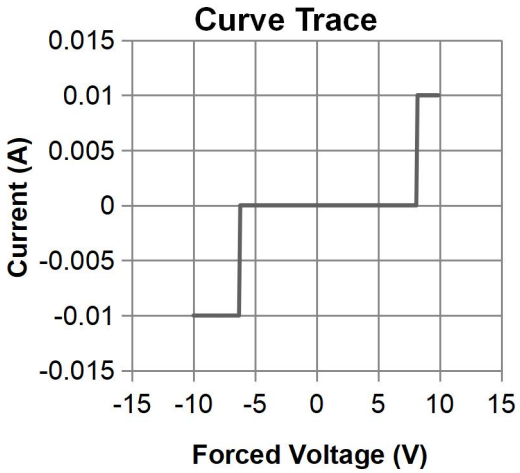


Fig.4 IV Curve

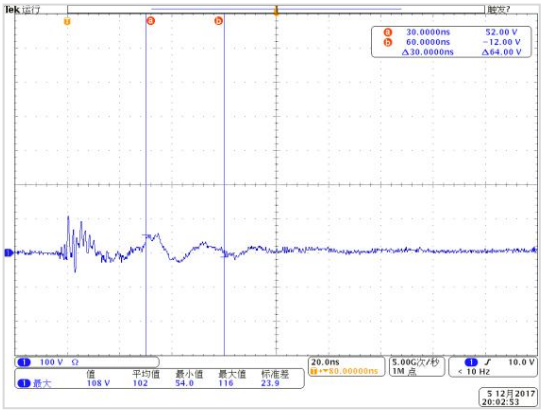


Fig.5 Clamping Voltage at IEC61000-4-2
+8kV Pulse Waveform

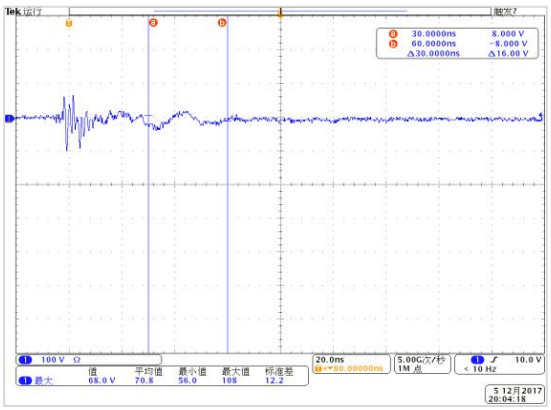
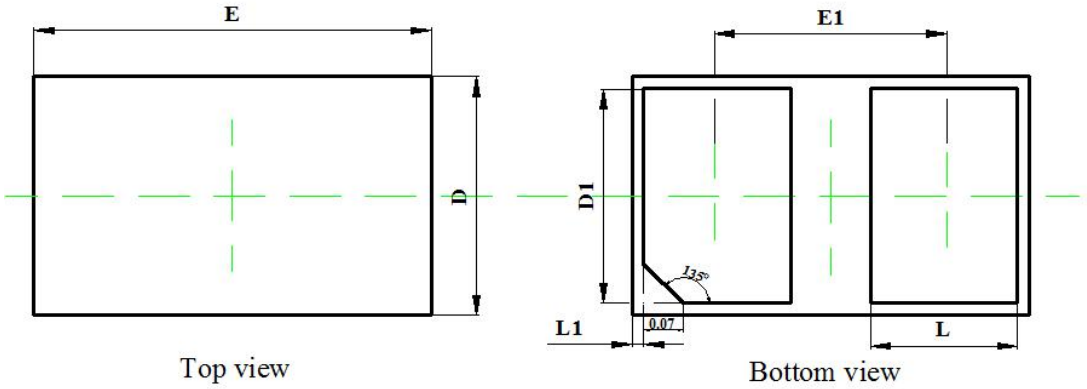
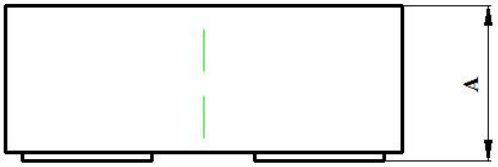


Fig.6 Clamping Voltage at IEC61000-4-2
-8kV Pulse Waveform

Package Outline Dimensions

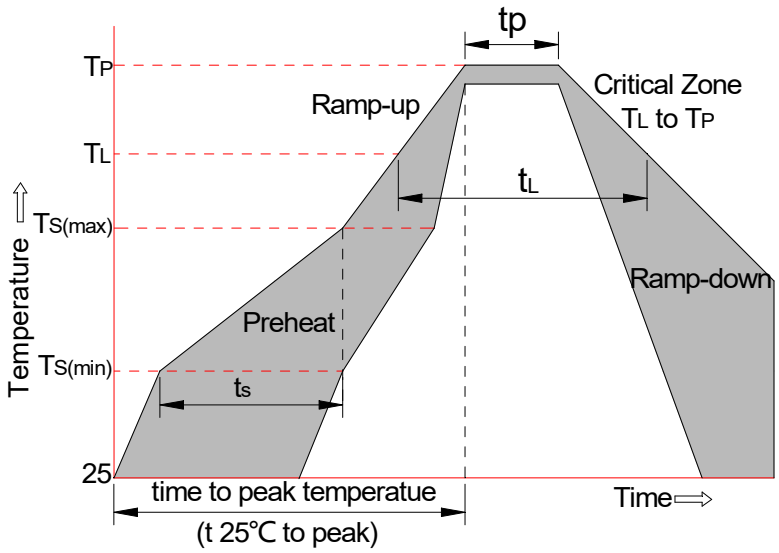
DFN1006 Package Outline





Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.320	0.420	0.013	0.017
D	0.550	0.650	0.022	0.026
E	0.950	1.050	0.037	0.041
D1	0.450	0.550	0.018	0.022
E1	0.550	0.650	0.022	0.026
L	0.280	0.380	0.011	0.015
L1	0.000	0.100	0.000	0.004

Soldering Parameters



Reflow Condition		Pb-Free Assembly
Pre-heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
xTime 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C

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